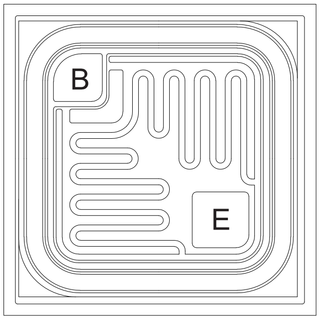
Central
Semiconductor Corp.
www.centralsemi.com

CP740V-2N5367

PNP - General Purpose Transistor Die
0.3 Amp, 40 Volt

The CP740V-2N5367 is a silicon PNP transistor designed for general purpose switching and amplifier applications.



BACKSIDE COLLECTOR R0

MECHANICAL SPECIFICATIONS:

Die Size	22 x 22 MILS
Die Thickness	7.1 MILS
Base Bonding Pad Size	3.7 x 3.7 MILS
Emitter Bonding Pad Size	4.2 x 4.2 MILS
Top Side Metalization	Al – 13,000Å
Back Side Metalization	Au – 9,000Å
Scribe Alley Width	1.97 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	35,100

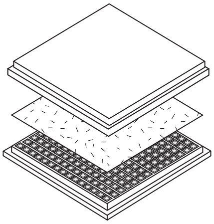
MAXIMUM RATINGS: (T_A=25°C)	**SYMBOL**		**UNITS**
Collector-Base Voltage	V_{CBO}	40	V
Collector-Emitter Voltage	V_{CEO}	40	V
Emitter-Base Voltage	V_{EBO}	4.0	V
Continuous Collector Current	I_C	300	mA
Continuous Collector Current (tp=10μs)	I_C	700	mA
Operating and Storage Junction Temperature	T_J, T_{stg}	-65 to +150	°C

ELECTRICAL CHARACTERISTICS: (T_A=25°C)

SYMBOL	**TEST CONDITIONS**	**MIN**	**TYP**	**MAX**	**UNITS**
I_{CBO}	V_{CB}=40V			100	nA
I_{CES}	V_{CE}=40V			100	nA
I_{EBO}	V_{EB}=4.0V			10	μA
BV_{CEO}	I_C=10mA	40			V
$V_{CE(SAT)}$	I_C=50mA, I_B=2.5mA			0.25	V
$V_{CE(SAT)}$	I_C=300mA, I_B=30mA			1.0	V
$V_{BE(SAT)}$	I_C=50mA, I_B=2.5mA			1.1	V
$V_{BE(SAT)}$	I_C=300mA, I_B=30mA			2.0	V
$V_{BE(ON)}$	V_{CE}=10V, I_C=2.0mA	0.5		0.8	V
h_{FE}	V_{CE}=10V, I_C=2.0mA	200			
h_{FE}	V_{CE}=1.0V, I_C=50mA	250		500	
h_{FE}	V_{CE}=5.0V, I_C=300mA	75			
h_{fe}	V_{CE}=10V, I_C=2.0mA, f=1.0kHz	200		750	
f_T	V_{CE}=10V, I_C=2.0mA		250		MHz

R1 (24-July 2019)

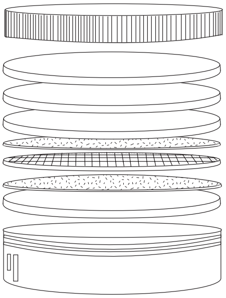
BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

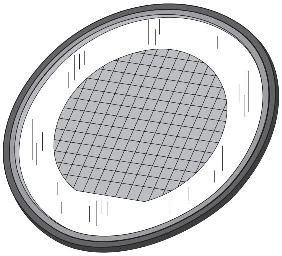
CT: Singulated die in tray (waffle) pack.
(example: CP211-<u>PART NUMBER</u>-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-<u>PART NUMBER</u>-CM)



UNSAWN WAFER

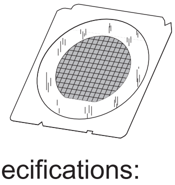
WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-<u>PART NUMBER</u>-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked.
(example: CP211-<u>PART NUMBER</u>-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centralsemi.com/bdspecs

R2 (3-April 2017)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp.
145 Adams Avenue
Hauppauge, NY 11788 USA
Main Tel: (631) 435-1110
Main Fax: (631) 435-1824
Support Team Fax: (631) 435-3388
www.centralsemi.com

Worldwide Field Representatives:
www.centralsemi.com/wwreps

Worldwide Distributors:
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